SPECIAL "MICROELECTRONICS" LABELS

1.0 SCOPE

This standard establishes special labeling requirements to be applied to packages, wraps, etc., containing MSD microelectronics parts, components, or assemblies.

2.0 REFERENCES

2.1 Lockheed Packaging Standard LPS 40–001 "General Requirement Specification"

2.2 Lockheed Product Protection Standard PPS–H325 "Microelectronics Parts and Assemblies (MSD use only)"

2.3 OD 14309 "Protection for FBM Material During Fabrication, Assembly, and Storage"

3.0 REQUIREMENTS

3.1 GENERAL

3.1.1 The microelectronics label requirements specified herein are in addition to any other container marking requirements imposed by the Procurement Document/Lockheed Packaging Standard (LPS).

3.1.2 The labels shall not cover other specified markings and shall not block inspection visibility on transparent packages.

3.2 MARKING – UNIT PACKAGES

Not Applicable

3.3 MARKING – INTERMEDIATE PACKAGES

3.3.1 Labels (See Figure 1) shall be affixed to each intermediate package.

3.3.2 When large size containers are included, apply additional microelectronics labels to opposite sides/ends of container to assure visibility.

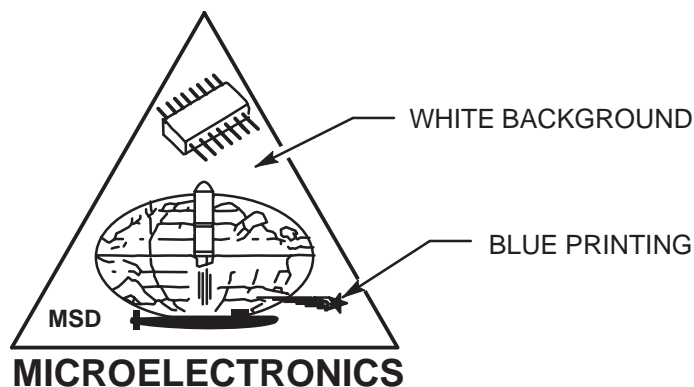3.3.3 Select and apply an appropriate size label(s) commensurate with the size of the container(s).

Figure 1. Illustration – Microelectronics   P10116–001

3.4 MARKING – SHIPPING CONTAINERS

3.4.1 Apply applicable size label(s) in accordance with Paragraph 3.3.

3.5 DESIGN CRITERIA

3.5.1 Pressure–Sensitive Label – blue on white background (see illustration).

4.0 QUALITY ASSURANCE

4.1 Labels and application of such labels shall be in accordance with this standard or shipments shall be subject to rejection and return to the supplier at his expense.

5.0 NOTES

5.1 <u>Standard Label Sizes:</u>

      a. Equilateral Triangle, 3–3/8"

      b. Equilateral Triangle, 1"

5.2 <u>Label Source </u>– Mabi Company, San Jose, CA 95110 (408) 293–5050